

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10551745			
<b>Filing Date:</b>				
<b>Title of Invention:</b>	Method for the multi-stage production of diffusion soldered connections for power components comprising semiconductors chips			
<b>First Named Inventor/Applicant Name:</b>	Edmund Riedl			
<b>Filer:</b>	Mark L. Gleason/Cindy Schlotz			
<b>Attorney Docket Number:</b>	I431.131.101/FIN 421 PCT/			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
Oath/decl > 30 months from priority date	1617	1	130	130
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130